

A

B

C

D

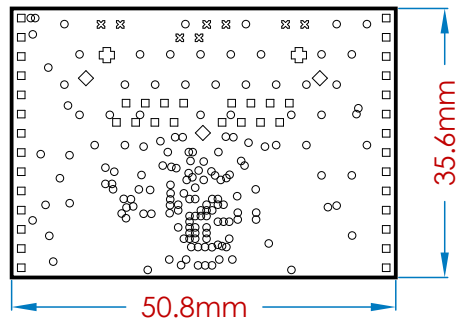
## Layer Stack Legend

Material	Layer	Thickness	Gerber
Surface Material	Top Overlay		GTO
Copper	Top Soldermask	0.010mm	GTS
Prepreg	Top Layer	0.035mm	GTL
Copper	Mid1	0.360mm	G1
Core		0.710mm	
Copper	Mid2	0.036mm	G2
Prepreg		0.360mm	
Copper	Bottom Layer	0.035mm	GBL
Surface Material	Bottom Soldermask	0.010mm	GBS
	Bottom Overlay		GBO
Total thickness: 1.592mm			

## Notes:

1. Use current revision of all standards.
2. Board is to be manufactured in accordance to IPC-6012 Class 2.
3. Laminate (core) and prepreg to be in accordance with IPC-4101/126
4. Board finish shall be ENIG
5. Soldermask colour shall be WHITE
6. Silkscreen colour shall be BLACK
7. All hole dimensions apply after plating
8. All copper dimensions apply after plating

## Drill Drawing View (Scale 1:1)



## Drill Table


Symbol	Count	Hole Size	Plated	Via / Pad	Hole Tolerance
○	162	0.20	Plated	Via	None
□	44	0.90	Plated	Pad	None
⊗	8	1.00	Plated	Pad	None
◇	3	1.60	Plated	Pad	None
⊕	2	3.25	Non-Plated	Pad	None
219 Total					

A

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D

Title			Fabrication Drawing		
Size A4	Revision V1.0	Project TMC8462A-BOB-ETH			
Date 2.08.2019 13:34	Sheet 1 of 3		 <p>Waterloohain 5 22769 Hamburg Germany tmc_info@trinamic.com</p>		
File TMC8462A-BOB-ETH-F.PCBDwf					

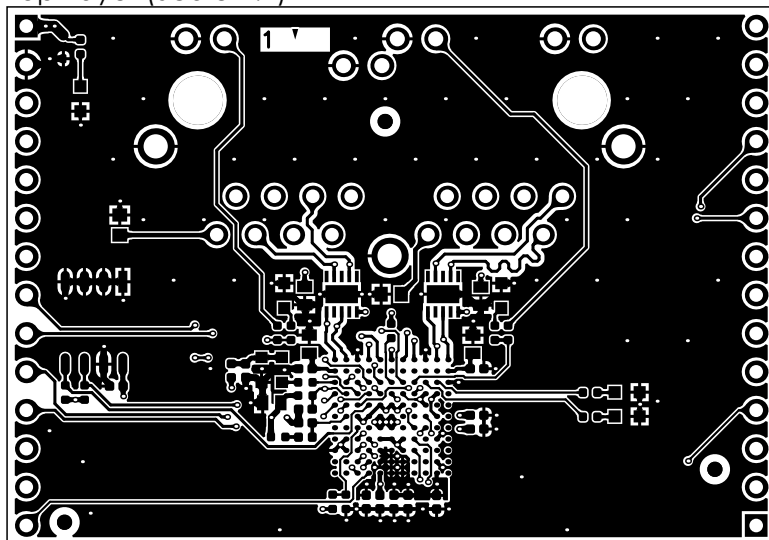
A

B

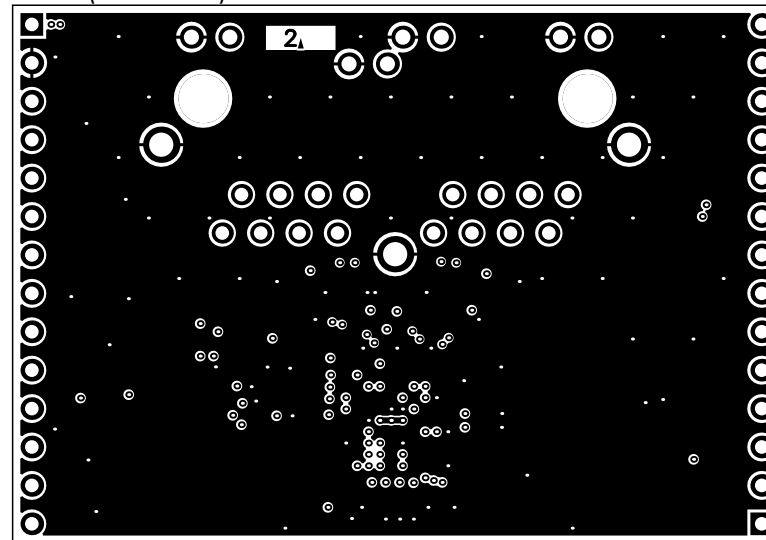
C

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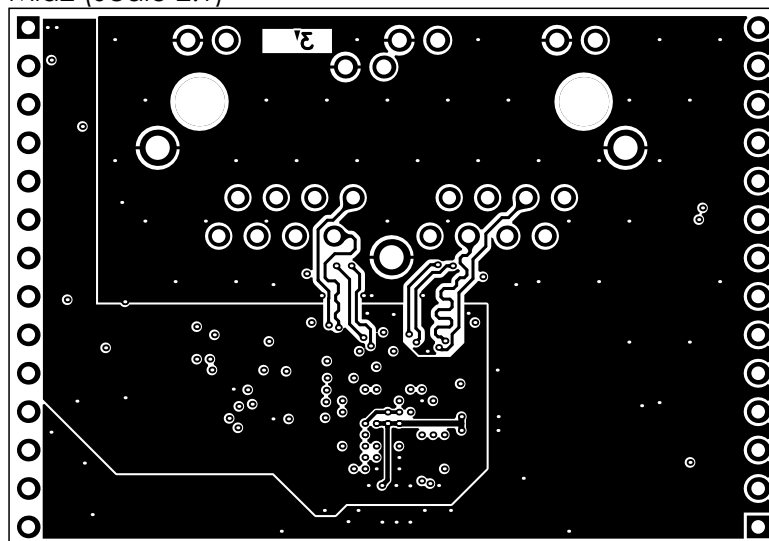
Top Layer (Scale 2:1)



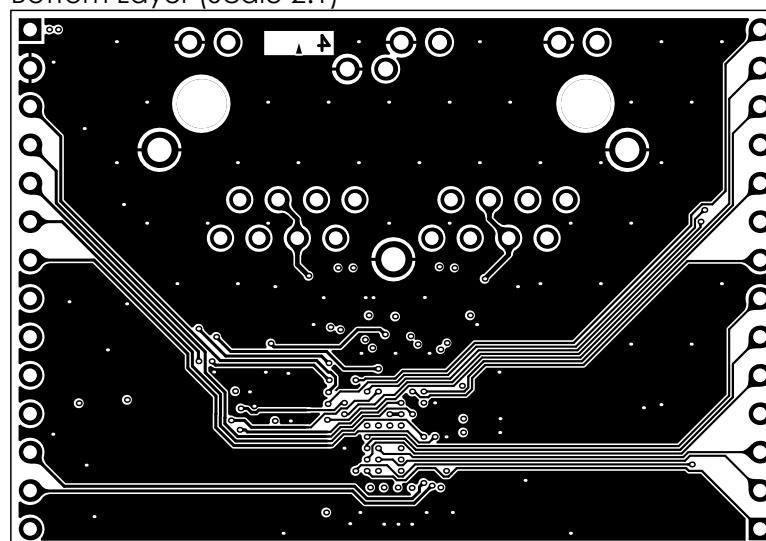
Mid1 (Scale 2:1)



Mid2 (Scale 2:1)



Bottom Layer (Scale 2:1)



Title		
Fabrication Drawing		
Size	Revision	Project
A4	V1.0	TMC8462A-BOB-ETH
Date	2.08.2019 13:34	Sheet 2 of 3
File	TMC8462A-BOB-ETH-F.PCBDwf	



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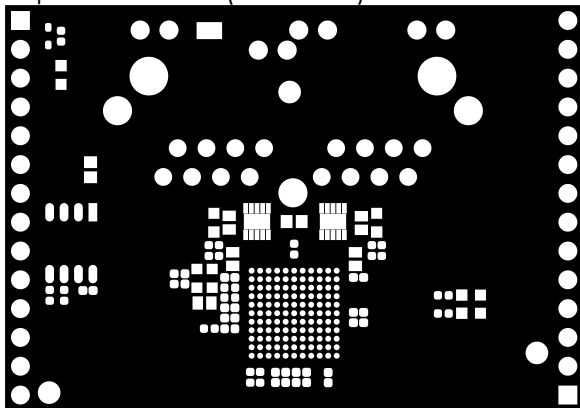
A

B

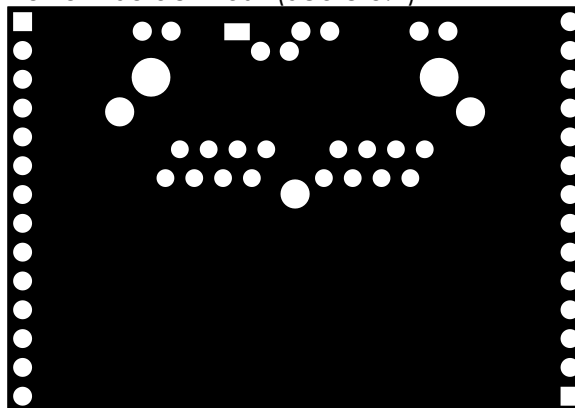
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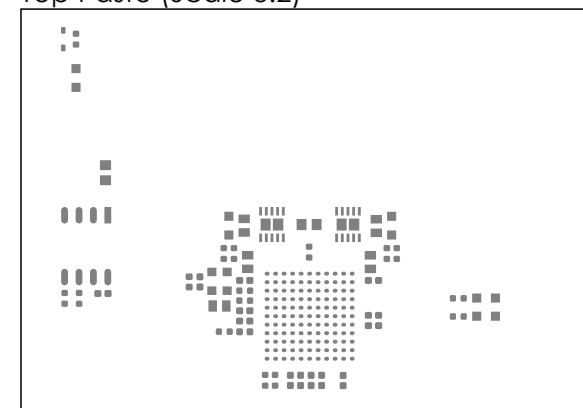
Top Soldermask (Scale 3:2)



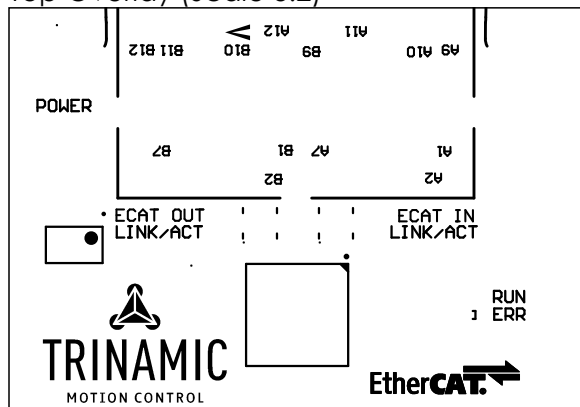
Bottom Soldermask (Scale 3:2)



Top Paste (Scale 3:2)



Top Overlay (Scale 3:2)



Bottom Overlay (Scale 3:2)

